
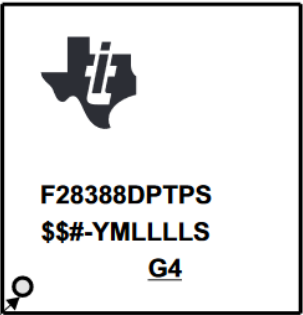


PCN Number:	20230815000.1		PCN Date:	August 16, 2023	
Title:	Qualification of LFAB as an additional Wafer Fab site option for select devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	Nov 16, 2023		Sample Requests accepted until:	Sep 16, 2023*	
*Sample requests received after September 16, 2023 will not be supported.					
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the addition of LFAB as an additional Wafer Fab site option for the products listed in the "Product Affected" section of this document.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
UMC12i	F65	300mm	LFAB	F65	300mm
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Device Symbol:					
<div style="display: flex; align-items: center;"> <div style="border: 1px solid black; padding: 10px; text-align: center; margin-right: 20px;">  F28388DPTPS \$\$-YMLLLS <u>G4</u> </div> <div> <p>YMLLLS = Lot Trace Code</p> <p>YM = 2-Digit Year/Month Code</p> <p>LLLL = Assembly Lot</p> <p>S = Assembly Site Code</p> <p>\$\$ = Wafer Fab Code as applicable</p> <p># = Silicon Revision Code</p> </div> </div>					
<div style="display: flex;"> <div style="margin-right: 20px;">  <p>Package Pin 1</p> </div> <div> <p>Original Fab Field:</p> <p>\$\$ = \$7 → UMC 12i</p> <p>Updated Fab Field:</p> <p>\$\$ = 3L → LFAB</p> </div> </div>					
Current Fab Site Information:					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
UMC12i	UMI	SGP	Singapore		

Additional Fab Site Information:

New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
LFAB	LHI	USA	Lehi

Sample product shipping label (not actual product label)

 **TEXAS INSTRUMENTS**
 MADE IN: Malaysia
 2DC: 20:
 MSL '2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM:
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

F28384DPTPS	F28385SZWTSR	F28388DPTPS	F28388SPTPSR
F28384DZWTS	F28386DPTPS	F28388DPTPSR	F28388SZWTS
F28384SPTPS	F28386DZWTS	F28388DZWTS	F28388SZWTSR
F28384SZWTS	F28386SPTPS	F28388DZWTSR	
F28385DZWTSR	F28386SZWTS	F28388SPTPS	

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: F28388DZWTS	Qual Device: F28388DPTPS	Wafer fProcess Qualification QBS Reference: TMS320F28379SPTPQ
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0
EDR	B3	Endurance and data retention	150C	1000 Hours			3/231/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0

- QBS: Qual By Similarity
- Qual Device F28388DZWTS is qualified at MSL3 260C
- Qual Device F28388DPTPS is qualified at MSL3 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2307-056

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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